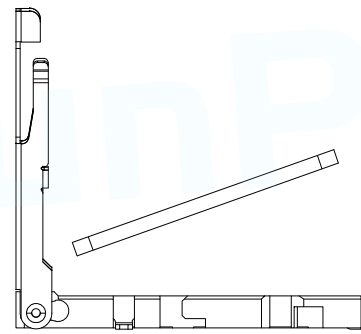
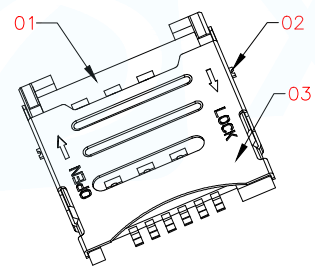
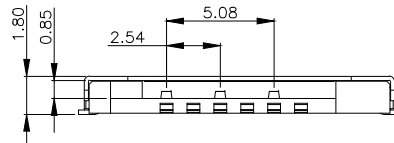
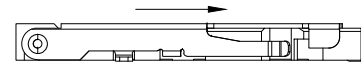


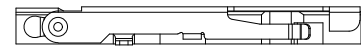
MICRO SIM



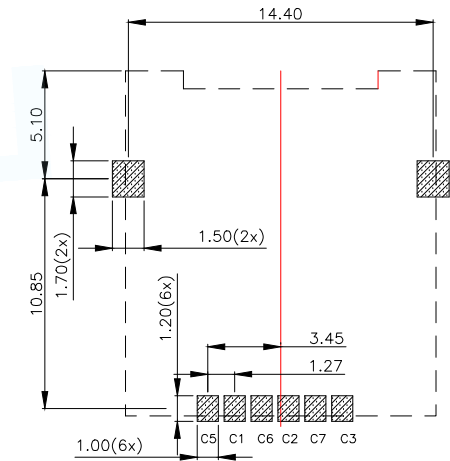
STEP 1 INSERT MICRO SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH



PAD AREA

KEEP OUT AREA

RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

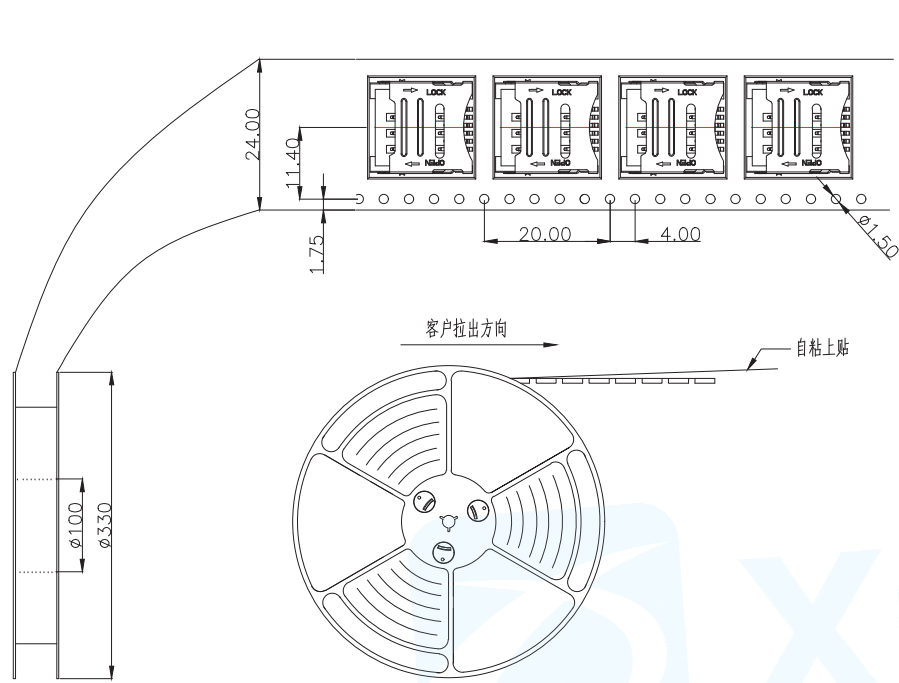
- 一、材质和镀涂:
1. 胶芯: LCP,UL 94V-0,黑色
  2. 端子: 磷铜C5210-H,T=0.15,  
全区镀底30u"MIN  
触点镀金GOLD FLASH0.6-1.0u"  
焊脚双面镀亮锡50-80u'
  3. 定位脚: 磷铜C2680-H,T=0.20,  
全区镀底30u"MIN,镀亮锡50-80u"
  4. 外壳: 不锈钢 T=0.2

- 二、技术参数:
- 接触电阻: 100mΩ MAX  
绝缘阻抗: 1000MΩ MIN(500DC)  
额定电流: 每个接触件1A MAX  
额定电压: 30V MAX(DC)  
耐压: 500V R.M.S/MIN  
使用温度: -40℃~85℃  
湿度: 80% R.H MAX  
寿命: >3000次

MICRO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

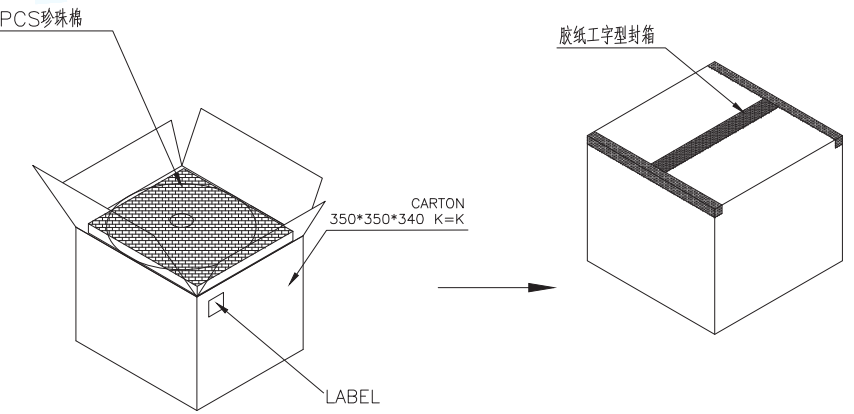
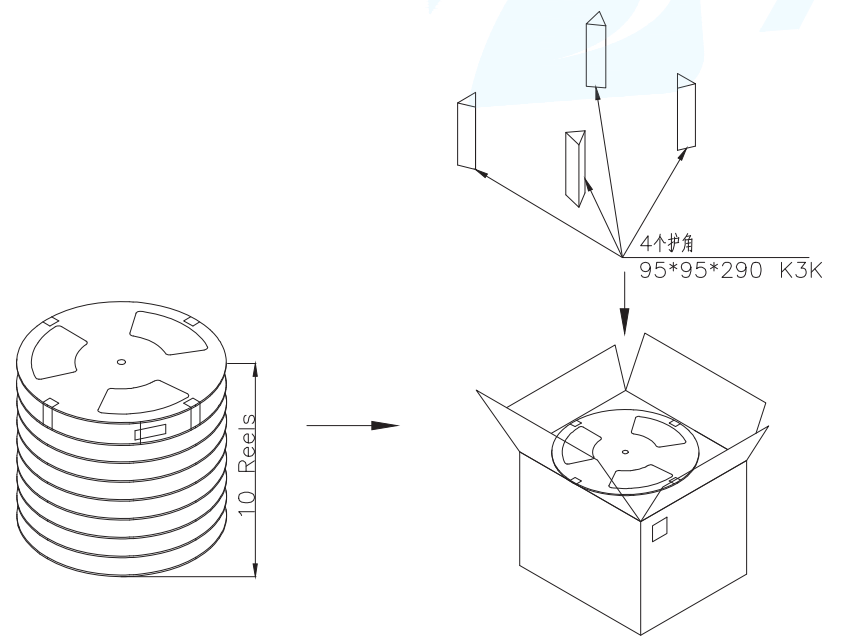
PIN NO.	NAME	PIN NO.	NAME
C1	VCC	C4	VPP
C2	GND	C5	CLK
C3	RST	C6	IO

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MICRO SIM CARD HINGED 6PIN H1.8 铰链式
DECIMALS:	ANGLES:		PAR SMC-216
X.:±0.50	X':±2°		DWN
X.X:±0.30	X.X':±1°		CHKD
X.XX:±0.20		APVD	SCALE:1:1 UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1
			REV:A



NOTES

1. 每卷包装数量: 1200PCS/每卷
2. 卷带包装方式:
3. 每箱包装数量: 12000PCS/箱
4. 纸箱350mm\*350mm\*440mm(内部尺寸), 材质K=K



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED		TITLE: MICRO SIM CARD HINGED 6PIN H1.8 微透式 包装图 PAR SMC-216 DWN CHKD APVD	
DECIMALS:	ANGLES:		
X.: ±0.50	X.: ±2°		
X.X: ±0.30	X.X': ±1°		
X.XX: ±0.20			
CUSTOMER COPY		SCALE: 1:1	UNIT: MM
		SIZE: A4	SHEET: 1F1
			REV: A